

Intel Platform Memory Operations

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Intel Platform Memory Operations

DDR3 1333 ECC UDIMM Validation Results 2DIMM/ch

Listed below are the results from a small sample of DDR3 1333 ECC UDIMM modules tested on reference server platforms based on Intel® C200 series chipsets using Intel® Xeon® E3-1200 series processors (codename Sandy Bridge), in a 2DIMMs/channel configuration. We are providing this information as a guide to module performance with Intel® reference platforms. This testing is not intended to replace the normal OEM component qualification process. For results on specific Intel® motherboards or OEM production motherboards, please refer to the OEM's list of qualified memory suppliers.

DDR3-1333 (9-9-9) UDIMM ECC, 2DIMM/ch – all parts DDR3 and DDR3L are tested at 1.5V

DIMM Supplier	DIMM Part #	DIMM Size	Raw Card	Native Voltage	Tested Speed	DRAM Supplier	DRAM Part #	DRAM Density	DRAM Width	DRAM Date
Elpida	EBJ20EF8BCFA-DJ-F	2GB	D	DDR3	1333 CL9	Elpida	EDJ2108BCSE-DJ-F	2Gb	X8	1051
Elpida	EBJ41EF8BCFA-DJ-F	4GB	E	DDR3	1333 CL9	Elpida	EDJ2108BCSE-DJ-F	2Gb	X8	1051
Hynix	HMT325U7BFR8C-H9	2GB	D	DDR3	1333 CL9	Hynix	H5TQ2G83BFR-H9C	2Gb	X8	1048
Hynix	HMT351U7BFR8C-H9	4GB	E	DDR3	1333 CL9	Hynix	H5TQ2G83BFR-H9C	2Gb	X8	1048
Hynix	HMT112U7TFR8C-H9	1GB	D	DDR3	1333 CL9	Hynix	H5TQ1G83TFR-H9C	1Gb	x8	1127
Hynix	HMT325U7CFR8C-H9	2GB	D	DDR3	1333 CL9	Hynix	H5TQ2G83CFR-H9C	2Gb	x8	1119
Hynix	HMT351U7CFR8C-H9	4GB	E	DDR3	1333 CL9	Hynix	H5TQ2G83CFR-H9C	2Gb	x8	1123
Hynix	HMT351U7CFR8A-H9	4GB	E	DDR3L	1333 CL9	Hynix	H5TC2G83CFR-H9A	2Gb	x8	1123
Kingston	KVR1333D3S3E9S/2G	2GB	D	DDR3	1333 CL9	Elpida	EDJ2108BCSE-DJ-F	2Gb	X8	1114
Kingston	KVR1333D3E9S/4G	4GB	E	DDR3	1333 CL9	Elpida	EDJ2108BCSE-DJ-F	2Gb	x8	1114
Micron	MT9JSF25672AZ-1G4D1	2GB	D	DDR3	1333 CL9	Micron	MT41J256M8HX-15E:D	2Gb	X8	1023

Intel Platform Memory Operations

Micron	MT18JSF51272AZ-1G4D1	4GB	E	DDR3	1333 CL9	Micron	MT41J256M8HX-15E:D	2Gb	X8	1023
Micron	MT18JSF51272AZ-1G6M1	4GB	E	DDR3	1333 CL9	Micron	MT41K256M8DA-125:M	2Gb	x8	1129
Micron	MT9JSF25672AZ-1G6M1	2GB	D	DDR3	1333 CL9	Micron	MT41K256M8DA-125:M	2Gb	x8	1129
Micron	MT18KSF51272AZ-1G4M1	4GB	E	DDR3L	1333 CL9	Micron	MT41K256M8DA-125:M	2Gb	x8	1129
Micron	MT9KSF25672AZ-1G4M1	2GB	D	DDR3L	1333 CL9	Micron	MT41K256M8DA-125:M	2Gb	x8	1129
Samsung	M391B2873GB0-CH9	1GB	D	DDR3	1333 CL9	Samsung	K4B1G0846G-BCH9	1Gb	x8	1104
Samsung	M391B5673GB0-CH9	2GB	E	DDR3	1333 CL9	Samsung	K4B1G0846G-BCH9	1Gb	x8	1125
Samsung	M391B5773CH0-CH9	2GB	D	DDR3	1333 CL9	Samsung	K4B2G0846C-HCH9	2Gb	X8	1112
Samsung	M391B5273CH0-CH9	4GB	E	DDR3	1333 CL9	Samsung	K4B2G0846C-HCH9	2Gb	X8	1112
Samsung	M391B1G73AH0-CH9	8GB	E	DDR3	1333 CL9	Samsung	K4B4G0846A-HCH9	4Gb	x8	1125
Samsung	M391B1G73BH0-CH9	8GB	E	DDR3	1333 CL9	Samsung	K4B4G0846B-HCH9	4Gb	x8	1113
Samsung	M391B1G73BH0-YH9	8GB	E	DDR3L	1333 CL9	Samsung	K4B4G0846B-HYH9	4Gb	x8	1110
Samsung	M391B5773DH0-CH9	2GB	D	DDR3	1333 CL9	Samsung	K4B2G0846D-HCH9	2Gb	x8	1040
Samsung	M391B5273DH0-CH9	4GB	E	DDR3	1333 CL9	Samsung	K4B2G0846D-HCH9	2Gb	x8	1040
Samsung	M391B2873FH0-CH9	1GB	D	DDR3	1333 CL9	Samsung	K4B1G0846F-HCH9	1Gb	x8	1046
Samsung	M391B5673FH0-CH9	2GB	E	DDR3	1333 CL9	Samsung	K4B1G0846F-HCH9	1Gb	x8	1046

Updated on September 2, 2011

Intel Platform Memory Operations

Approved test labs

The following test labs have the capability of performing DDR3 UDIMM system-level testing. For further information, please contact:

Advanced Validation Labs

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